

Abstract of the Disclosure:

An electronic component includes a semiconductor chip which has an active upper side and a passive rear side. The semiconductor chip is surrounded by a sawn edge. This edge of 5 semiconductor material has profile-sawn contours. The profile-sawn contours are surrounded by a plastics composition forming an edge of plastic. The plastics composition is in form-locking engagement with the profile-sawn contours. A method of producing a component of this type is also provided.

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